High-speed diode

BAW62

FEATURES

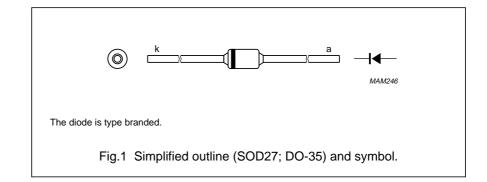
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 75 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

- · High-speed switching
- Fast logic applications.

DESCRIPTION

The BAW62 is a high-speed switching diode fabricated in planar technology, and encapsulated in the hermetically sealed leaded glass SOD27 (DO-35) package.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		_	75	V
V _R	continuous reverse voltage		_	75	V
I _F	continuous forward current	see Fig.2; note 1	_	250	mA
I _{FRM}	repetitive peak forward current		_	450	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	4	A
		t = 1 ms	_	1	A
		t = 1 s	_	0.5	A
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	350	mW
T _{stg}	storage temperature		-65	+200	°C
Tj	junction temperature		_	200	°C

Note

1. Device mounted on an FR4 printed circuit-board; lead length 10 mm.

1996 Sep 17

2

Philips Semiconductors Product specification

High-speed diode

BAW62

ELECTRICAL CHARACTERISTICS

 T_j = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
		I _F = 5 mA	620	750	mV
		I _F = 100 mA	_	1000	mV
		I _F = 100 mA; T _j = 100 °C	_	930	mV
I _R	reverse current	see Fig.5			
		V _R = 20 V	_	25	nA
		V _R = 50 V	_	200	nA
		V _R = 75 V	_	5	μΑ
		V _R = 20 V; T _j = 150 °C	_	50	μΑ
		V _R = 75 V; T _j = 150 °C	_	100	μΑ
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	_	2	pF
t _{rr}	reverse recovery time	when switched from I _F = 10 mA to	_	4	ns
		I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7			
V _{fr}	forward recovery voltage	when switched from $I_F = 50$ mA; $t_r = 20$ ns; see Fig.8	_	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R _{th j-a}	thermal resistance from junction to ambient	lead length 10 mm; note 1	500	K/W

Note

1. Device mounted on a printed circuit-board without metallization pad.

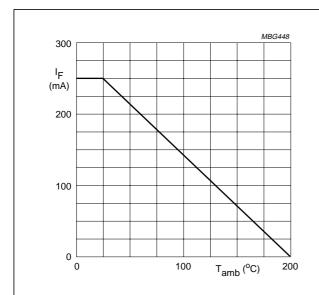
1996 Sep 17 3

Philips Semiconductors Product specification

High-speed diode

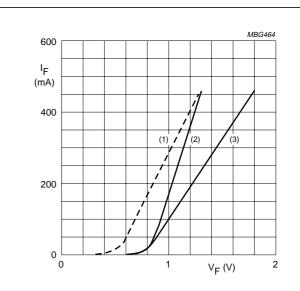
BAW62

GRAPHICAL DATA



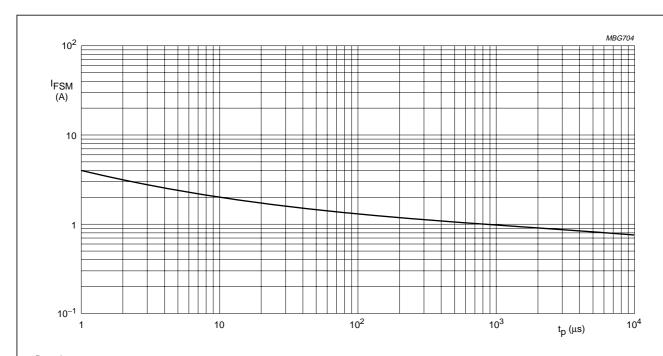
Device mounted on an FR4 printed-circuit board; lead length 10 mm.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) T_j = 175 °C; typical values.
- (2) $T_j = 25 \,^{\circ}\text{C}$; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



Based on square wave currents.

 T_j = 25 °C prior to surge.

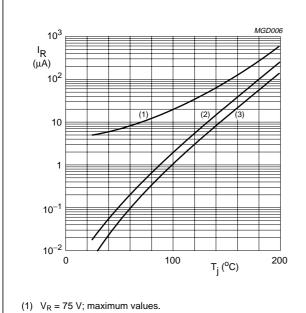
Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

1996 Sep 17 4

Philips Semiconductors Product specification

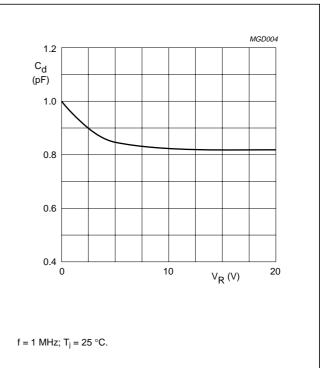
High-speed diode

BAW62



- (2) $V_R = 75 \text{ V}$; typical values.
- (3) $V_R = 20 \text{ V}$; typical values.

Reverse current as a function of junction temperature.



Diode capacitance as a function of reverse voltage; typical values.